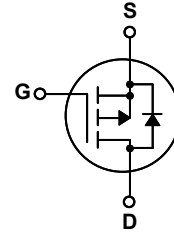


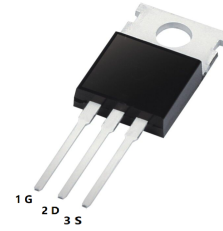
Description

These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.



Features

- V_{DS} (V) = -60V
- I_D = -13.5A (V_{GS} = -10V)
- $R_{DS(ON)}$ < 70m Ω (V_{GS} = -10V)



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQP27P06	Unit
V_{DSS}	Drain-Source Voltage	-60	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	-27	A
	- Continuous ($T_C = 100^\circ\text{C}$)	-19.1	A
I_{DM}	Drain Current - Pulsed (Note 1)	-108	A
V_{GSS}	Gate-Source Voltage	± 25	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	560	mJ
I_{AR}	Avalanche Current (Note 1)	-27	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	12	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	-7.0	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	120	W
	- Derate above 25°C	0.8	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	FQP27P06	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.25	$^\circ\text{C/W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	$^\circ\text{C/W}$

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = -250 μA	-60			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = -250 μA, Referenced to 25°C		-0.06		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -60 V, V _{GS} = 0 V			-1	μA
		V _{DS} = -48 V, T _C = 150°C			-10	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250 μA	-1.1	-2	-3.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = -10 V, I _D = -13.5 A		55	70	mΩ
g _{FS}	Forward Transconductance	V _{DS} = -30 V, I _D = -13.5 A		12.4		S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -25 V, V _{GS} = 0 V, f = 1.0 MHz		1100	1400	pF
C _{oss}	Output Capacitance			510	660	pF
C _{rss}	Reverse Transfer Capacitance			120	155	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = -30 V, I _D = -13.5 A, R _G = 25 Ω (Note 4)		18	45	ns
t _r	Turn-On Rise Time			185	380	ns
t _{d(off)}	Turn-Off Delay Time			30	70	ns
t _f	Turn-Off Fall Time			90	190	ns
Q _g	Total Gate Charge	V _{DS} = -48 V, I _D = -27 A, V _{GS} = -10 V (Note 4)		33	43	nC
Q _{gs}	Gate-Source Charge			6.8		nC
Q _{gd}	Gate-Drain Charge			18		nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current				-27	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				-108	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -27 A			-4.0	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = -27 A, dI _F / dt = 100 A/μs		105		ns
Q _{rr}	Reverse Recovery Charge			0.41		μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 0.9\text{ mH}, I_{AS} = -27\text{ A}, V_{DD} = -25\text{ V}, R_G = 25\text{ }\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq -27\text{ A}, di/dt \leq 300\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Essentially independent of operating temperature

Typical Characteristics

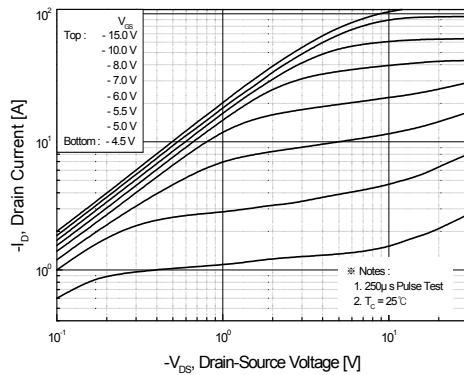


Figure 1. On-Region Characteristics

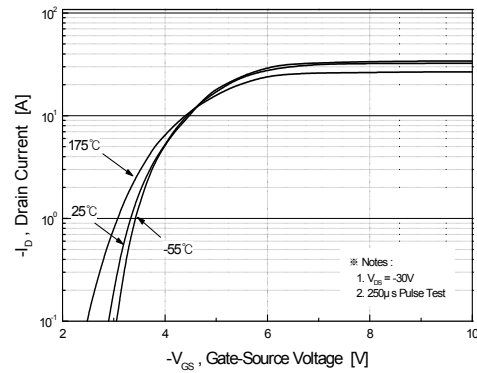


Figure 2. Transfer Characteristics

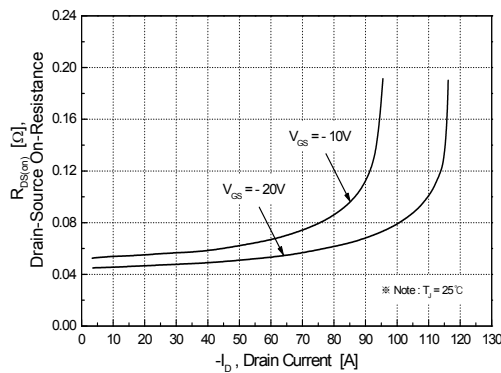


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

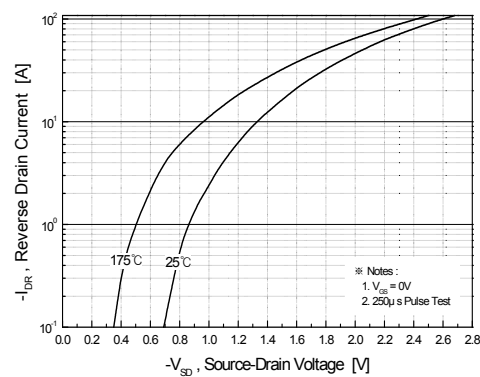


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

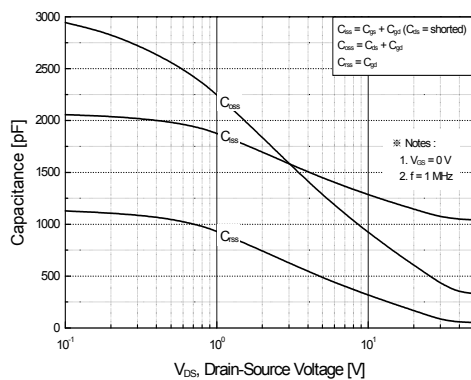


Figure 5. Capacitance Characteristics

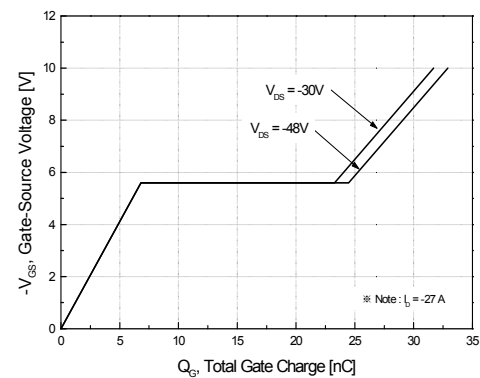


Figure 6. Gate Charge Characteristics

Typical Characteristics

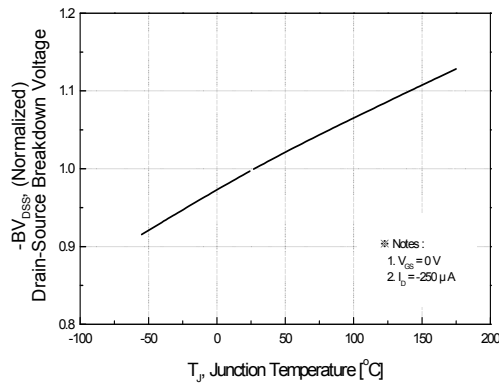


Figure 7. Breakdown Voltage Variation vs. Temperature

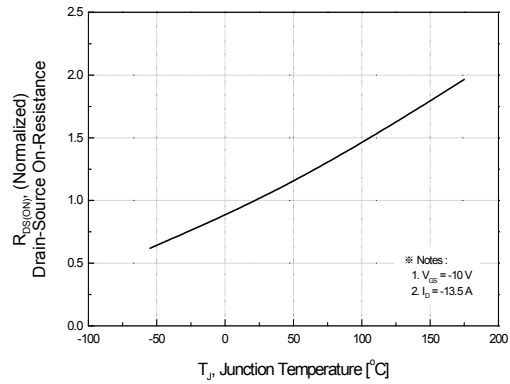


Figure 8. On-Resistance Variation vs. Temperature

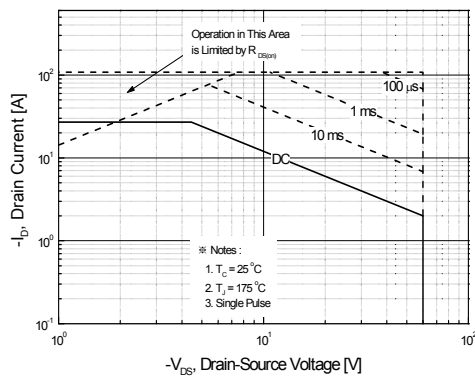


Figure 9. Maximum Safe Operating Area

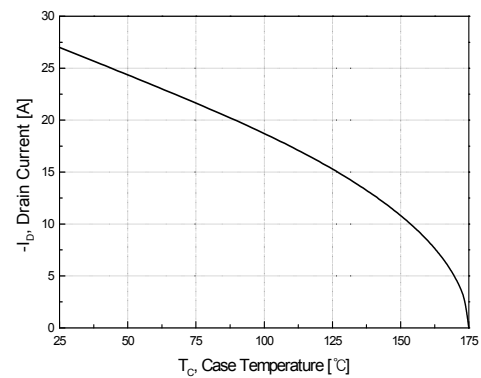


Figure 10. Maximum Drain Current vs. Case Temperature

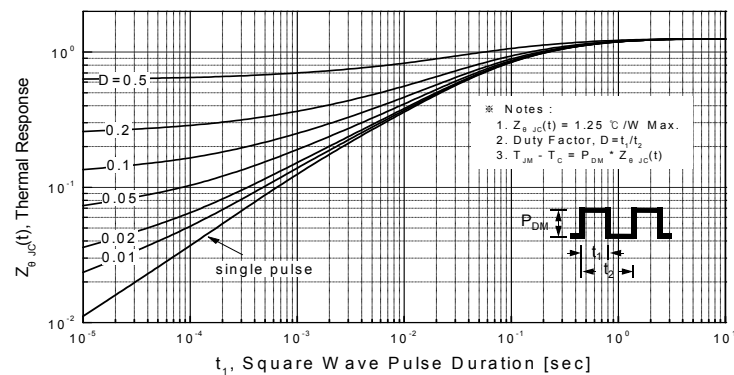
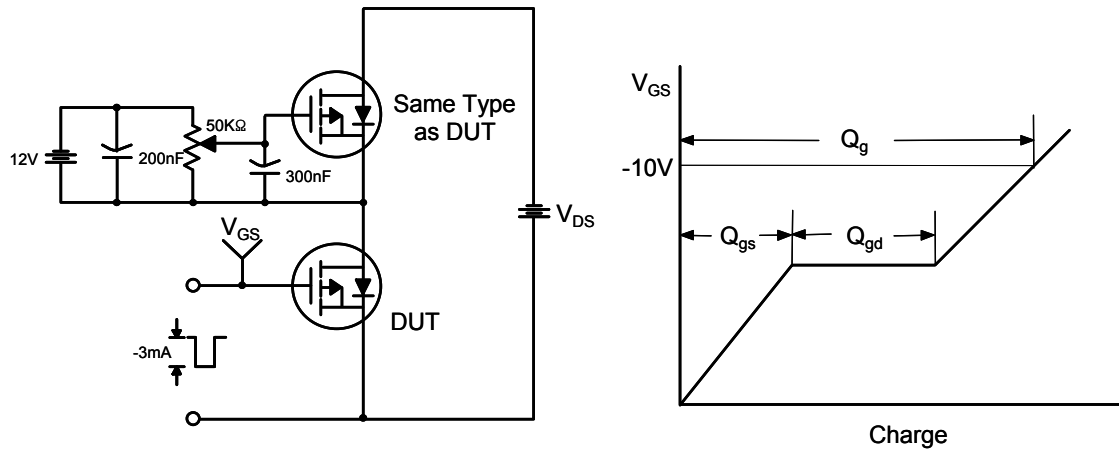
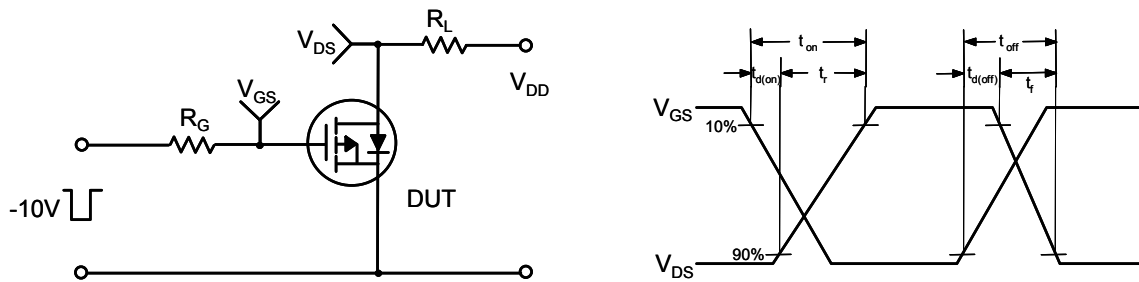


Figure 11. Transient Thermal Response Curve

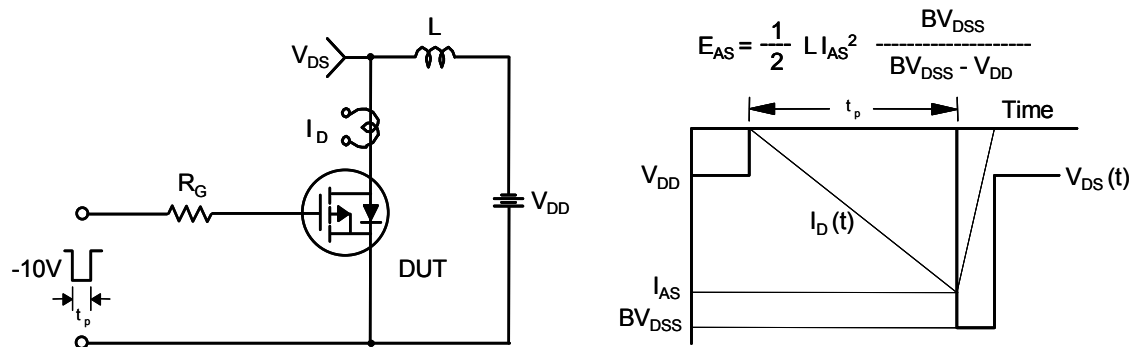
Gate Charge Test Circuit & Waveform



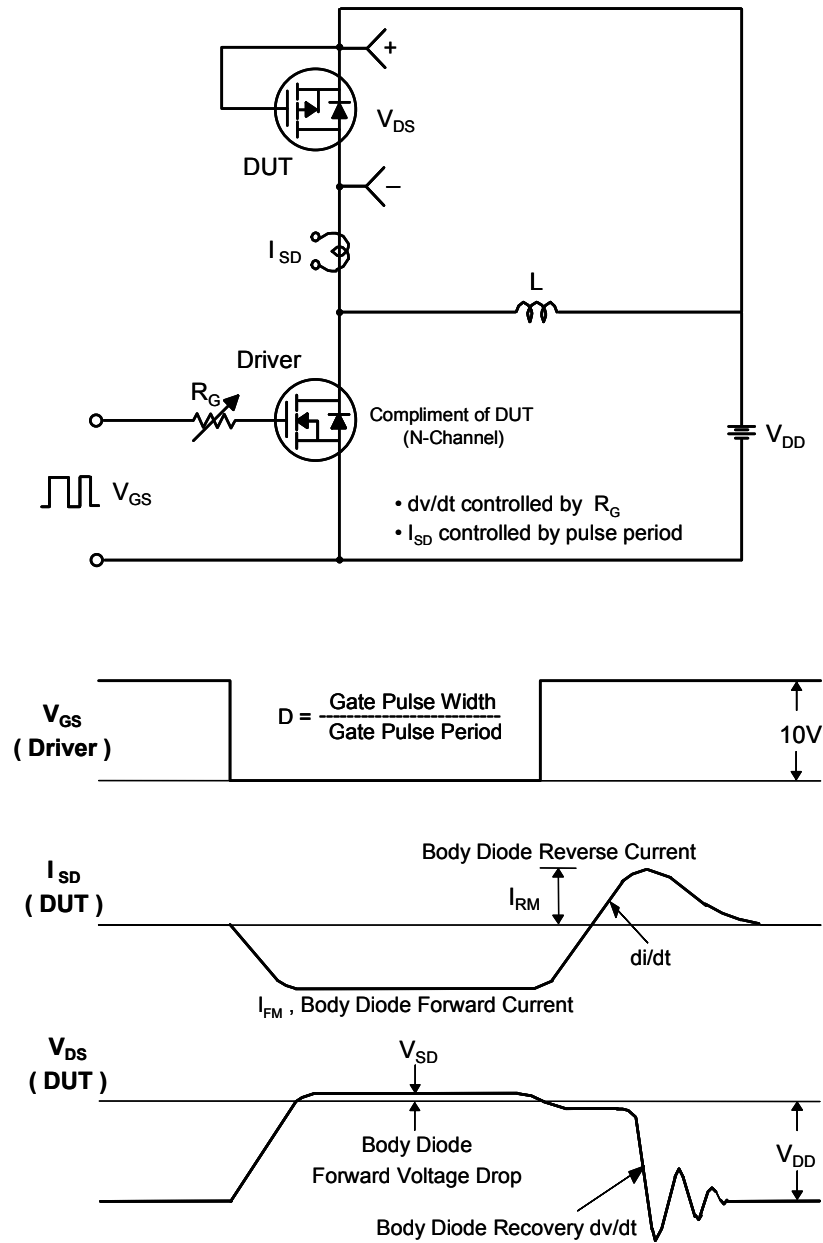
Resistive Switching Test Circuit & Waveforms



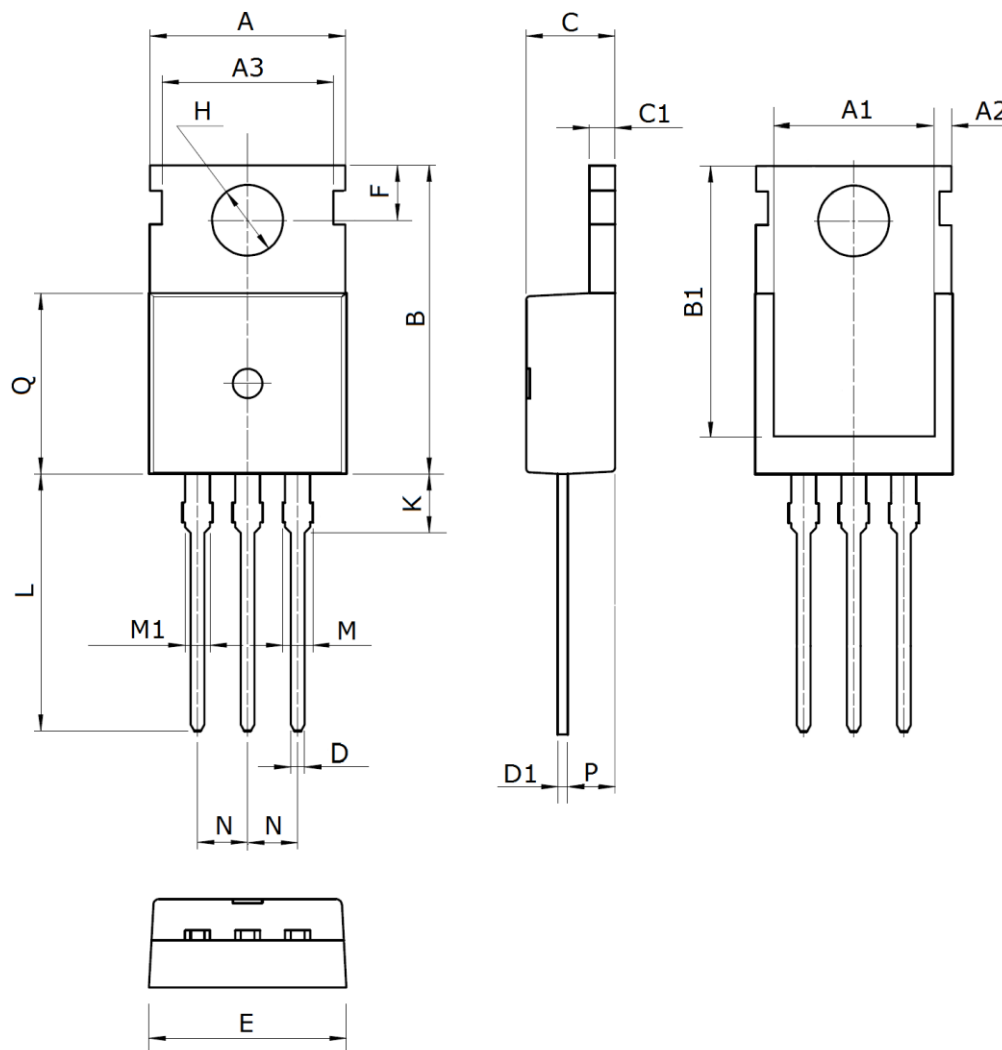
Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

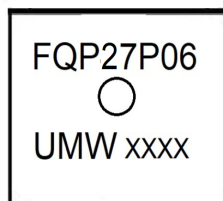


Package Mechanical Data TO-220



Symbol	Dimensions (mm)	Symbol	Dimensions (mm)	Symbol	Dimensions (mm)
A	10.0±0.3	C1	1.3±0.2	L	13.2±0.4
A1	8.0±0.2	D	0.8±0.2	M	1.38±0.1
A2	0.94±0.1	D1	0.5±0.1	M1	1.28±0.1
A3	8.7±0.1	E	10.0±0.3	N	2.54(typ)
B	15.6±0.4	F	2.8 ±0.1	P	2.4±0.3
B1	13.2±0.2	H	3.6±0.1	Q	9.15±0. 25
C	4.5±0. 2	K	3.1±0.2		

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
UMW FQP27P06	TO-220	1000	Tape and reel